

ABSTRACT OF THE DISCLOSURE

This polyimide film is superior in heat resistance, rigidity and high frequency properties, is free of 5 inconveniences due to curling even when various functional layers are laminated by heating, and is preferable as a substrate film superior in thermal degradation stability for electronic parts. This polyimide film has a planar orientation coefficient of 10 0.79-0.89 as measured by an X-ray diffraction method, a difference in the surface planar orientation degree between one surface thereof and the other surface thereof of not more than 2 and a curling degree of not more than 5%, which is obtained by imidation of a 15 polyimide precursor film having a particular imidation rate.